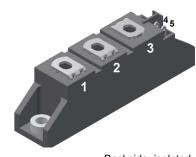
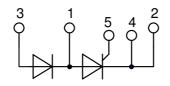
## MCNA55PD2200TB

High Voltage Thyristor \ Diode Module	$V_{\text{RRM}}$	<i>=</i> 2x 2200 V	
	I <sub>tav</sub>	=	55 A
	V <sub>T</sub>	=	1.2 V
Phase leg			

Part number MCNA55PD2200TB



Backside: isolated **E**72873



### Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al2O3-ceramic

### **Applications:**

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

### Package: TO-240AA

- Isolation Voltage: 4800 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

### Terms Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office. Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office. Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747and per semiconductor unless otherwise specified

# LIXYS

# MCNA55PD2200TB

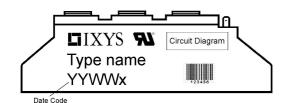
Definition max. non-repetitive reverse/forward b max. repetitive reverse/forward block reverse current, drain current	0 0	$T_{VJ} = 25^{\circ}C$	min.	typ.	<b>max.</b> 2300	Uni
max. repetitive reverse/forward block	0 0	$T_{VJ} = 25^{\circ}C$			0000	
,	ina voltage				2300	
reverse current, drain current	e e	$T_{VJ} = 25^{\circ}C$			2200	
	$V_{R/D} = 2200 V$	$T_{VJ} = 25^{\circ}C$			100	μ
	V <sub>R/D</sub> = 2200 V	$T_{VJ} = 140^{\circ}C$			10	m
forward voltage drop	I <sub>τ</sub> = 55 A	$T_{VJ} = 25^{\circ}C$			1.23	
	$I_{T} = 110 \text{ A}$				1.48	'
	I <sub>τ</sub> = 55 A	T <sub>vJ</sub> = 125 °C			1.20	1
	I <sub>τ</sub> = 110 A				1.56	,
average forward current	T <sub>c</sub> = 85°C	T <sub>vJ</sub> = 140°C			55	
RMS forward current	180° sine				86	1
threshold voltage		T <sub>v1</sub> = 140°C			0.84	Ņ
slope resistance { for power loss	calculation only	٧J			6.5	m
thermal resistance junction to case						K/V
				0.20		K/V
		$T_{0} = 25^{\circ}C$		0.20	230	V
	$t = 10 \text{ ms} \cdot (50 \text{ Hz}) \text{ sing}$					k/
						k/
						N/
						ļ
under for funitor						
value for fusing						1
						kA <sup>2</sup>
						i.
					3.52	1
junction capacitance	$V_R = 700 V$ f = 1 MHz			28		р
max. gate power dissipation	t <sub>P</sub> = 30 μs	$T_c = 140 ^{\circ}C$			10	۷
	t <sub>P</sub> = 300 μs				5	v
average gate power dissipation					0.5	V
critical rate of rise of current	T <sub>vJ</sub> = 140 °C; f = 50 Hz rep	petitive, $I_{T} = 165 A$			150	Α/μ
	$t_{P}$ = 200 µs; di <sub>G</sub> /dt = 0.45 A/µs;					
	$I_{G} = 0.45 \text{ A}; V = \frac{2}{3} V_{DRM}$ nor	n-repet., $I_{\tau} = 55 \text{ A}$			500	A/μ
critical rate of rise of voltage	$V = \frac{2}{3} V_{\text{DBM}}$	T <sub>v.i</sub> = 140°C			1000	V/µ
	$R_{GK} = \infty$ ; method 1 (linear voltag	e rise)				
gate trigger voltage					1.5	١
						١
gate trigger current	$V_{r} = 6 V$					m/
gale ligger carrent	• <u> </u>					i.
aate non-trigger voltage	$V = \frac{2}{\sqrt{3}}$					1
	$\mathbf{v}_{\mathrm{D}} = 73  \mathbf{v}_{\mathrm{DRM}}$	$1_{VJ} = 140 \text{ C}$				1
	10	T 0500				<u> </u>
latching current	r ·	$I_{VJ} = 25^{\circ}C$			200	m
						1
						m
gate controlled delay time		$T_{VJ} = 25 \degree C$			2	μ
	$I_{G} = 0.45 \text{ A}; \ di_{G}/dt = 0.45 \text{ A}/\mu \text{s}$					   
turn-off time	$V_{R} = 100 \text{ V}; I_{T} = 55 \text{ A}; \text{ V} = \frac{2}{3}$	V <sub>DRM</sub> T <sub>VJ</sub> = 125 °C		500		μ
	RMS forward current         threshold voltage slope resistance       for power loss         thermal resistance junction to case thermal resistance case to heatsink         total power dissipation         max. forward surge current         value for fusing         junction capacitance         max. gate power dissipation         average gate power dissipation         critical rate of rise of current	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c c c c c c c } & I = 110 \text{ A} \\ \hline \\ \hline \\ average forward current & T_c = 85^\circ \text{C} & T_{vJ} = 140^\circ \text{C} \\ \hline \\ RMS forward current & 180^\circ \text{ sine} & \\ \hline \\ \hline \\ Tv_{vJ} = 140^\circ \text{C} \\ \hline \\ slope resistance \\ slope resistance \\ slope resistance iunction to case \\ \hline \\ thermal resistance case to heatsink \\ \hline \\ total power dissipation & T_c = 25^\circ \text{C} \\ \hline \\ max. forward surge current & t = 10 \text{ ms}; (50 \text{ Hz}), sine & T_{vJ} = 45^\circ \text{C} \\ \hline \\ t = 8,3 \text{ ms}; (60 \text{ Hz}), sine & T_{vJ} = 45^\circ \text{C} \\ \hline \\ t = 8,3 \text{ ms}; (60 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 8,3 \text{ ms}; (60 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 10 \text{ ms}; (50 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 10 \text{ ms}; (50 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 10 \text{ ms}; (50 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 10 \text{ ms}; (50 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 8,3 \text{ ms}; (60 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 8,3 \text{ ms}; (60 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 8,3 \text{ ms}; (60 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 8,3 \text{ ms}; (60 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 8,3 \text{ ms}; (60 \text{ Hz}), sine & T_{vJ} = 140^\circ \text{C} \\ \hline \\ t = 30  \mu \text{S} \\ average gate power dissipation \\ \hline \\ cirtical rate of rise of current & T_{vJ} = 140^\circ \text{C}; f = 50 \text{ Hz} \\ repetitive, \ \\ I_{c} = 0.45 \text{ A}; (0_{c})(\text{d} = 0.45 \text{ A}) (\text{ms}; \hline \\ \hline \\ \hline \\ cirtical rate of rise of voltage & V = 3^\circ \text{V}_{\text{DRM}} & \text{T}_{vJ} = 165 \text{ A} \\ \hline \\ \\ \hline \\ cirtical rate of rise of voltage & V_0 = 6 \text{ V} \\ \hline \\ \hline \\ \hline \\ \ \\ f_{cirt} = -0.45 \text{ A}; \ \\ \hline \\ \hline \\ \ \\ gate non-trigger voltage & V_0 = 6 \text{ V} \\ \hline \\ \hline \\ \hline \\ \hline \\ \ \\ \ \\ \ \\ \end{tabular} \text{ T}_{vJ} = 25^\circ \text{C} \\ \hline \\ \hline \\ \hline \\ \hline \\ \ \\ \ \\ \ \\ \end{tabular} \text{ trigger current} \\ \hline \\ \hline \\ \hline \\ \ \\ \ \\ \ \\ \end{tabular} \text{ trigger current} \\ \hline \\ \hline \\ \ \\ \ \\ \ \\ \ \\ \ \\ \ \\ \ \\ \$	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	$ \begin{array}{c c c c c c c c c c c c c c c c c c c $

 $\ensuremath{\mathsf{IXYS}}$  reserves the right to change limits, conditions and dimensions.

# XYS

# MCNA55PD2200TB

Package TO-240AA			Ratings					
Symbol	Definition	Conditions			min.	typ.	max.	Unit
I <sub>RMS</sub>	RMS current	per terminal					200	Α
T <sub>vj</sub>	virtual junction temperature				-40		140	°C
T <sub>op</sub>	operation temperature				-40		125	°C
T <sub>stg</sub>	storage temperature				-40		125	°C
Weight						81		g
M <sub>D</sub>	mounting torque				2.5		4	Nm
M <sub>T</sub>	terminal torque				2.5		4	Nm
d <sub>Spp/App</sub>	creepage distance on surface   striking distance through a		terminal to terminal	13.0	9.7			mm
<b>d</b> <sub>Spb/Apb</sub>	creepage distance on surrac	e   striking uistance through an	terminal to backside	16.0	16.0			mm
	isolation voltage t = 1 second	t = 1 second			4800			V
	t = 1 minute		50/60 Hz, RMS; liso∟ ≤ 1 mA		4000			V



### Part description

M = Module

C = Thyristor (SCR)N = High Voltage Thyristor

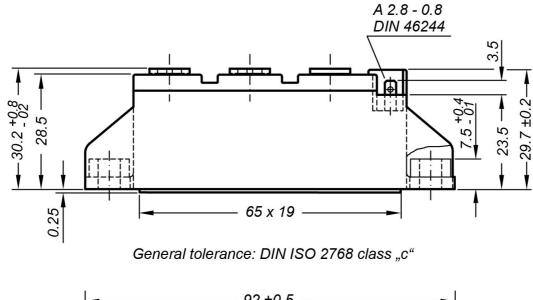
A = (>= 2000V) 55 = Current Rating [A] PD = Phase leg

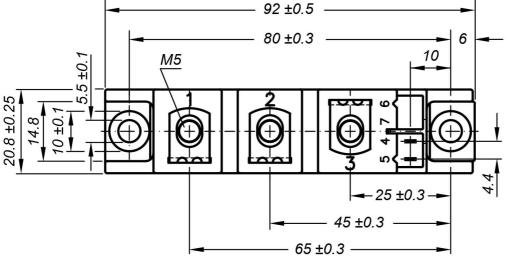
2200 = Reverse Voltage [V] TB = TO-240AA-1B

Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.	
Standard	MCNA55PD2200TB	MCNA55PD2200TB	Box	36	521042	

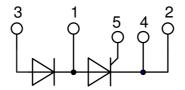
Equiv	alent Circuits for	Simulation	* on die level	T <sub>vJ</sub> = 140 °C
	)- <u>R</u>	Thyristor		
V <sub>0 max</sub>	threshold voltage	0.84		V
$\mathbf{R}_{0 \max}$	slope resistance *	5.3		mΩ

## Outlines TO-240AA



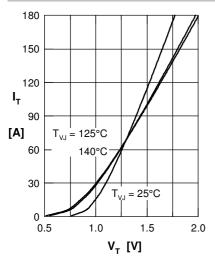


Optional accessories: Keyed gate/cathode twin plugs Wire length: 350 mm, gate = white, cathode = red UL 758, style 3751 Type **ZY 200L** (L = Left for pin pair 4/5)



## MCNA55PD2200TB

### Thyristor



1000

800

600

400

200

100.0

10.0

1.0

0.1

0.01

0.10

t<sub>gd</sub>

ITSM

[A]

50 Hz, 80% V

140°C

0.1

t [s]

 $I_{TSM}$ : crest value, t: duration

T<sub>VJ</sub> = 25°C

lim

typ.

10.00

1.00

I<sub>G</sub> [A]

Fig. 2 Surge overload current

T<sub>VJ</sub>

0.01

Fig. 1 Forward characteristics

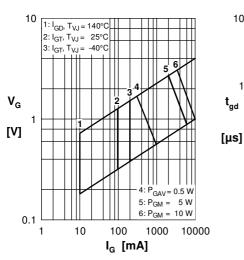
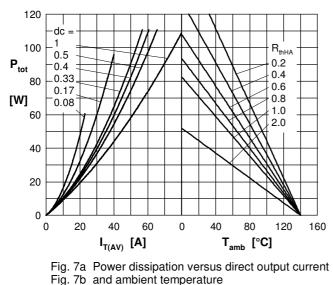
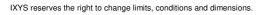


Fig. 4 Gate voltage & gate current





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